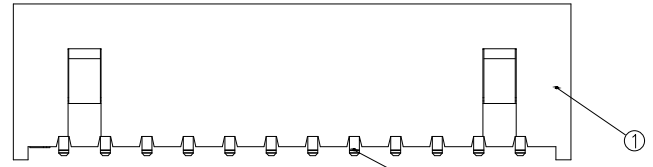
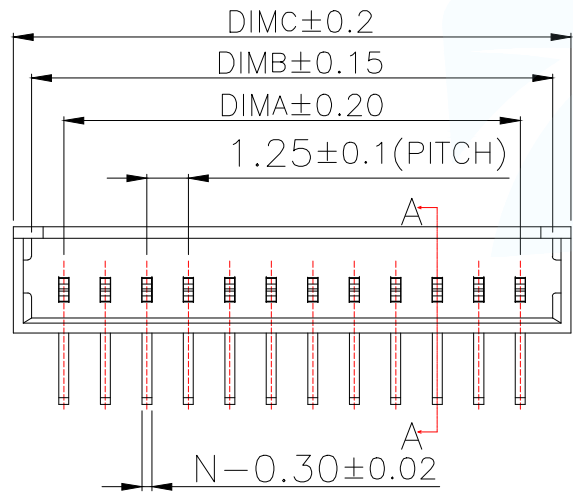
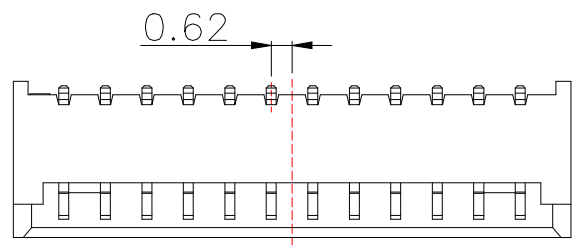
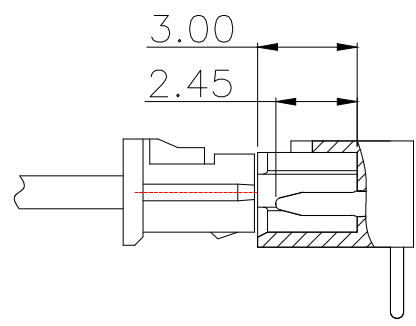
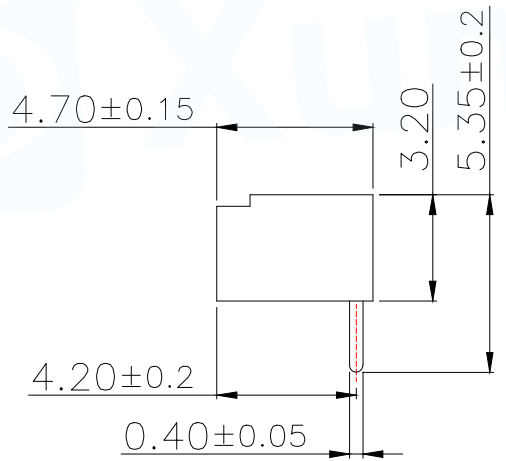


LOCK CONFIGURATION (锁扣位置)



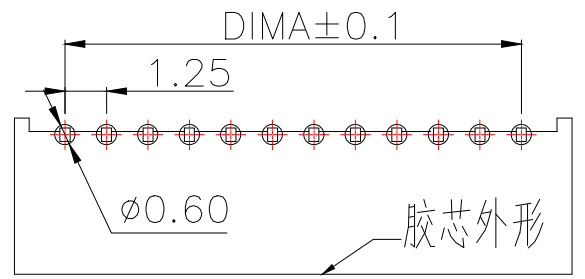
序号	品名	材质
1	1.25 Pitch R/A Wire To Board Housing DIP(H=3.2)	PA66 UL94V-2 Yellow
2	1.25 Pitch R/A Wire To Board Terminal DIP(H=3.2)	Copper Alloy/ Tin Plating

Technical Index:
 1.The surface of the plastic parts should be smooth,no rough edges,no obvious shrinkage,defects,cracks and other phenomena)
 2.Lock Configuration: 2 to 3Pin is 1, ≥ 4Pin is 2
 3.Temperature range: -25°C~+85°C.
 4.Rated voltage: 125V, AC/DC.
 5.Contact resistance: ≤0.02Ω.
 6.Insulation resistance: ≥100MΩ



SECTION A-A

Part No	Pin	A	B	C
WAFER-MX1.25-2PWZ-H62	2	1.25	3.20	4.30
WAFER-MX1.25-3PWZ-H62	3	2.50	4.45	5.55
WAFER-MX1.25-4PWZ-H62	4	3.75	5.70	6.80
WAFER-MX1.25-5PWZ-H62	5	5.00	6.95	8.05
WAFER-MX1.25-6PWZ-H62	6	6.25	8.20	9.30
WAFER-MX1.25-7PWZ-H62	7	7.50	9.45	10.55
WAFER-MX1.25-8PWZ-H62	8	8.75	10.70	11.80
WAFER-MX1.25-9PWZ-H62	9	10.00	11.95	13.05
WAFER-MX1.25-10PWZ-H62	10	11.25	13.20	14.30
WAFER-MX1.25-11PWZ-H62	11	12.50	14.45	15.55
WAFER-MX1.25-12PWZ-H62	12	13.75	15.70	16.80
WAFER-MX1.25-13PWZ-H62	13	15.00	16.95	18.05
WAFER-MX1.25-14PWZ-H62	14	16.25	18.20	19.30
WAFER-MX1.25-15PWZ-H62	15	17.50	19.45	20.55
WAFER-MX1.25-16PWZ-H62	16	18.75	20.70	21.80
WAFER-MX1.25-17PWZ-H62	17	20.00	21.95	23.05
WAFER-MX1.25-18PWZ-H62	18	21.25	23.20	24.30
WAFER-MX1.25-19PWZ-H62	19	22.50	24.45	25.55
WAFER-MX1.25-20PWZ-H62	20	23.75	25.70	26.80



适用线路板(PCB LAYOUT)

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:1.25 PITCH H3.2 R/A WIRE TO BOARD DIP CONN.
DECIMALS:	ANGLES:		PAR WAFER-MX1.25-NPWZ-H62
X.:±0.50	X'::±5°		DWN
.X:±0.20	X.X'::±3°		CHKD
.XX:±0.10	X.XX'::±1°	APVD	SCALE:1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	SHEET:1F1 REV:A